

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Paul A. Farrar  
Serial No.: 10/634,274  
Filed: August 05, 2003  
Title: H2 Plasma Treatment

Examiner: Brook Kebede  
Group Art Unit: 2823  
Docket: 1303.110US1

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**SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT**

MS Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicant respectfully requests that this Supplemental Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicant requests that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicant with the next official communication.

Pursuant to 37 C.F.R. §1.97(b), it is believed that no fee or statement is required with the Supplemental Information Disclosure Statement. However, if an Office Action on the merits has been mailed, the Commissioner is hereby authorized to charge the required fees to Deposit Account No. 19-0743 in order to have this Supplemental Information Disclosure Statement considered.

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

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The Examiner is invited to contact the Applicant's Representative at the below-listed telephone number if there are any questions regarding this communication.

The present application is either a U.S. national patent application filed after June 30, 2003 or an international application that entered the national stage under 35 U.S.C. § 371 after June 30, 2003. Thus, Applicant believes that the U.S. Patent & Trademark Office has waived the requirement under 37 C.F.R. 1.98 (a)(2)(i) for submitting a copy of each cited U.S. patent and each U.S. patent application publication. The waiver is provided in a pre-OG notice from the U.S. Patent & Trademark Office entitled "Information Disclosure Statements May Be Filed Without Copies of U.S. Patents and Published Applications in Patent Applications filed after June 30, 2003" and dated July 11, 2003. Applicant acknowledges the requirement to submit copies of foreign patent documents and non-patent literature in accordance with 37 C.F.R. 1.98(a)(2).

Respectfully submitted,

PAUL A. FARRAR

By his Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.  
P.O. Box 2938  
Minneapolis, MN 55402  
(612) 371-2157

Date 7 September 2004

By David R. Cochran  
David R. Cochran  
Reg. No. 46,632

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: MS Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 7 day of September, 2004.

Name

Tina Kohel

Signature

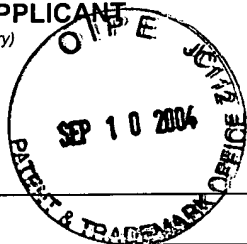
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Substitute for form 1449A/PTO

**INFORMATION DISCLOSURE  
STATEMENT BY APPLICANT**

(Use as many sheets as necessary)



Complete if Known

Application Number	10/634,274
Filing Date	August 5, 2003
First Named Inventor	Farrar, Paul
Group Art Unit	2823
Examiner Name	Kebede, Brook

Sheet 1 of 1

Attorney Docket No: 1303.110US1

**US PATENT DOCUMENTS**

Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	Filing Date If Appropriate
	US-6,208,016	03/27/2001	Farrar, Paul	257	643	02/24/1999
	US-6,288,442	09/11/2001	Farrar, Paul A.	257	678	09/10/1998
	US-6,358,849	03/19/2002	Havemann, R. H., et al.	438	689	12/21/1999
	US-6,552,432	04/22/2003	Farrar, Paul A.	257	751	08/30/2001
	US-6,614,099	09/02/2003	Farrar, Paul A.	257	643	09/04/2001
	US-6,743,716	06/01/2004	Farrar, Paul A.	438	652	07/16/2002
	US-6,756,298	06/29/2004	Ahn, Kie Y., et al.	438	635	08/01/2002

**EXAMINER****DATE CONSIDERED**

Substitute Disclosure Statement Form (PTO-1448)

\* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. † Applicant's unique citation designation number (optional) ‡ Applicant is to place a check mark here if English language Translation is attached



S/10/634,274

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Applicant: Paul A. Farrar

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Serial No.: 10/634,274

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Title: H2 PLASMA TREATMENT

COMMUNICATION CONCERNING RELATED APPLICATION(S)

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Applicant would like to bring to the Examiner's attention the following related application(s) in the above-identified patent application:

<u>Serial/Patent No.</u>	<u>Filing Date</u>	<u>Attorney Docket</u>	<u>Title</u>
09/483869 6420262	January 18, 2000	303.664US1	STRUCTURES AND METHODS TO ENHANCE COPPER METALLIZATION
09/484002 6376370	January 18, 2000	303.673US1	PROCESS FOR PROVIDING SEED LAYERS FOR USING ALUMINUM, COPPER, GOLD AND SILVER METALLURGY
10/117041	April 5, 2002	303.673US2	INTEGRATED CIRCUIT AND SEED LAYERS
10/196078 6743716	July 16, 2002	303.664US2	STRUCTURES AND METHODS TO ENHANCE COPPER METALLIZATION
10/196081	July 16, 2002	303.664US3	STRUCTURES AND METHODS TO ENHANCE COPPER METALLIZATION
10/195965	July 16, 2002	303.664US4	STRUCTURES AND METHODS TO ENHANCE COPPER METALLIZATION
09/534224 6426289	March 24, 2000		
10/137293	May 3, 2002		
08/892114 6077792	July 14, 1997		
09/480290	January 10, 2000		

COMMUNICATION CONCERNING RELATED APPLICATIONS

Serial Number: 10/634,274

Filing Date: August 5, 2003

Title: H2 PLASMA TREATMENT

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10/789882	February 27, 2004	303.673US3	INTEGRATED CIRCUIT AND SEED LAYERS
10/854552	May 26, 2004	303.664US5	STRUCTURES AND METHODS TO ENHANCE COPPER METALLIZATION
09/534224 6426289	March 24, 2000		
10/137293	May 3, 2002		
08/892114 6077792	July 14, 1997		
09/480290	January 10, 2000		

Respectfully submitted,

PAUL A. FARRAR

By Applicant's Representatives,

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Date 7 September 2004 By David R. Cochran  
David R. Cochran  
Reg. No. 46,632

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 7 day of September, 2004.

Name

Tina Kohut

Signature

[Signature]